

# RN00382

## EtherCAT<sup>®</sup> Protocol Software Stack for Sub-Device

Rev. 3.0 — 12 December 2025

Release notes

### Document information

Information	Content
Keywords	RN00382, EtherCAT, protocol software stack, MIMXRT1180-EVK
Abstract	This document is the release notes for the EtherCAT protocol software stack for sub-device. Supports: MIMXRT1180-EVK.



## 1 Features

[Table 1](#) lists the features for EtherCAT protocol software stack subdevice.

**Table 1. Features**

Feature	Support
Mailbox protocol	Yes
CANopen over the EtherCAT	Yes
EtherCAT state machine	Yes
Bootstrap mode	Yes
CoE object dictionary	Yes
CoE service data object (SDO) communication	Yes
SDO expedited transfer	Yes
SDO normal transfer	Yes
SDO segmented transfer	Yes
SDO complete access	Yes
SDO info service	Yes
CoE emergency producer	Yes
File access over the EtherCAT	Yes
Ethernet over the EtherCAT	Yes
Synchronization manager	4
Distributed clocks	Yes
SM-Synchronization	Yes
DC-Synchronization	Yes
EEPROM PDI access	Yes
EEPROM emulation	Yes
Transmit PDOs	512
Receive PDOs	512
PDO transmission over synchronization manager	Yes
Dynamic PDO mapping	Yes
Mailbox watchdog monitoring	Yes
Usage of CANopen profiles	Yes
MII Management (Phy Access)	Yes
Acknowledge by write	Yes
Explicit device identification	Yes
Run and error LED emulation	Yes
Modular device profile	Yes (third-party stack required) (currently only supported for Non-GOAL version)
Safety over the EtherCAT (FSoE)	Yes (third-party stack required) (currently only supported for Non-GOAL version)

**Note:** The demo version of the software libraries has no feature restrictions, but are limited to a runtime of five hours.

## 2 Known restrictions

[Table 2](#) lists the known restrictions for EtherCAT protocol software stack subdevice.

Table 2. Known restrictions

Feature	Support
Servo drive over the EtherCAT	No
Vendor Specific over the EtherCAT	No
ADS over the EtherCAT	No
PDO transmission over a mailbox	No

## 3 Changelog and open issues

The following is the list of the changelog and open issues.

### • Changelog:

- Fixed write access to Register Media Independent Interface (MII) Management PDI Access State.
- Extended check of process data object (PDO) mapping objects to full address ranges (0x1600, 0x17FF, 0x1A00, and 0x1BFF).
- Check if the mailbox synchronization managers are in the Mailbox mode.
- Process fragmented CoE responses before sending EOE frame (do not interrupt Segmented SDO download or upload).
- Improved LED Emulation for Error LED on ET1100.
- Optionally support early access check for SDO downloads (Abort invalid access early, after the first chunk was received).
- Added the EtherCAT bootloader mode (FoE only) (No CoE, SDO, DC, or PDO).
- Reworked LED emulation to support the STATUS indicator.
- Fixed handling of NMT Split state when DC is enabled and active.
- Increase DC synchronization loss check time to 100 ms.
- Distinguish between loss of DC event and loss of PDI event when reporting an error.
- String values of IdentityObject are not set properly.
  - The EtherCAT stack did not consider default values passed with the parameters of the function `goal_ecatdynOdSubIndexAdd` for objects of data type `GOAL_ECAT_DATATYPE_VISSTRING`. The issue is now fixed by strcpy these values.
- SDO: Complete access download to a nonnumeric object can cause buffer overflow
  - If a SDO download request with Complete Access was received for an object that contains at least one nonnumeric subindex, a buffer overflow can occur.
- Stack does not support mapping of more than 255 PDOs in one direction.
  - The stack cannot handle PDO mappings where the number of combined PDO entries for one direction exceeds the number 255.

### • Open issues

Mapping objects to TX and RX PDOs can impact EtherCAT stack performance, especially in multicore setups with CM33 and CM7 cores. Such mappings can introduce performance degradation and limit achievable cycle times. To ensure optimal operation, maintain cycle times greater than 50 ms.

## 4 Revision history

[Table 3](#) summarizes the revisions to this document.

Table 3. Revision history

Document ID	Release date	Description
RN00382 v.3.0	12 December 2025	Initial public release

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